10/002,925

L Number	Hits	Search Text	DB	Time stamp
1	838	(stack\$3 near3 (chip die dice wafer semiconductor IC (integrated adj	USPAT;	2004/02/18 10:44
		circuit))) and @ad<19990503 and shield\$3	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
2	97	(stack\$3 near3 (chip die dice wafer semiconductor IC (integrated adj	USPAT;	2004/02/18 10:45
		circuit))) and @ad<19990503 and (shield\$3 near4 (wall side outside	US-PGPUB,	
		exterior))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	174	berezny-nema.xa.	USPAT;	2004/02/18 09:53
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
_	0	berezny-nema.xa.	US-PGPUB	2004/02/17 11:02
_	141078	transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	USPAT;	2004/02/17 11:49
	141070	dice chip IC (integrated adj circuit))	US-PGPUB,	200 110 2111 11115
		dice only to (integrated adj onedity)	ЕРО; ЛРО;	
	•		DERWENT;	
			IBM_TDB	
	217	(transmit\$4 and receiv\$3 and @ad<10000503 and (camicanductor dia	USPAT;	2004/02/17 11:51
-	317	(transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	US-PGPUB;	2004/02/17 11:31
		dice chip IC (integrated adj circuit))) and (chip near3 stack\$3)		
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	2004/02/17 12 21
-	14	((transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	USPAT;	2004/02/17 12:21
		dice chip IC (integrated adj circuit))) and (chip near3 stack\$3)) and	US-PGPUB;	
-		deactivat\$3	EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
	4	(("5444387") or ("5229647")).PN.	USPAT;	2004/02/17 14:48
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
.	0	tranceiver and @ad<19990503 and (stack\$3 near3 (semiconductor die	USPAT;	2004/02/17 14:54
		dice chip IC (integrated adj circuit) wafer))	US-PGPUB;	
			ЕРО; ЈРО;	
	*		DERWENT;	
			IBM TDB	
.	1190	transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 14:54
	1170	(semiconductor die dice chip IC (integrated adj circuit) wafer))	US-PGPUB;	
		(ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
	486	(transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 14:55
	700	(semiconductor die dice chip IC (integrated adj circuit) wafer))) and	US-PGPUB;	
		interconnect\$3	EPO; JPO;	
		Intercontitioning	DERWENT;	
			IBM_TDB	
	177	((transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 15:01
-	17	((transmits4 and receives and (wad<19990303 and (stacks3 hears (semiconductor die dice chip IC (integrated adj circuit) wafer))) and	US-PGPUB;	2007/02/17 13.01
			ЕРО; ЛРО;	
		interconnect\$3) and deactivat\$3		
			DERWENT;	
			IBM_TDB	2004/02/17 17 1
-	316	((transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 17:14
		(semiconductor die dice chip IC (integrated adj circuit) wafer))) and	US-PGPUB;	
		interconnect\$3) and (test\$3 fail\$3 bad malfunction\$3)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	1572	((438/109) or (257/777)).CCLS.	USPAT;	2004/02/17 17:14
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	762	(((438/109) or (257/777)).CCLS.) and @ad<19990503	USPAT;	2004/02/17 17:15
			US-PGPUB;	
		·	ЕРО; ЈРО;	
	1		DERWENT;	
		The state of the s	IBM_TDB	
-	83	(((((438/109) or (257/777)).CCLS.) and @ad<19990503) and (shield\$3	USPAT;	2004/02/17 17:15
		emf emi interference)	US-PGPUB;	
			ЕРО; ЈРО;	
	1		DERWENT;	
	1		IBM_TDB	